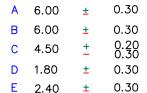
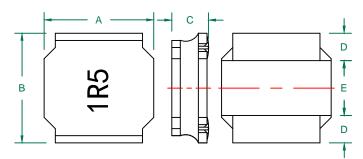
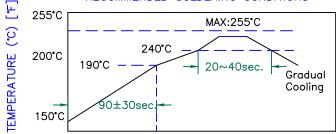
# TYS60451R5N-10

### PHYSICAL DIMENSIONS:

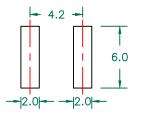


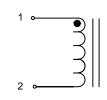


### RECOMMENDED SOLDERING CONDITIONS



## LAND PATTERNS FOR REFLOW SOLDERING

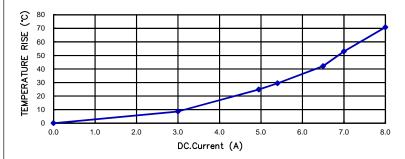




### **ELECTRICAL SPECIFICATION**

	Min	Nom	Max
INDUCTANCE (uH) L @ 100KHz/1V ± 30%	1.05	1.50	1.95
DCR (Ω)		0.012	0.0156

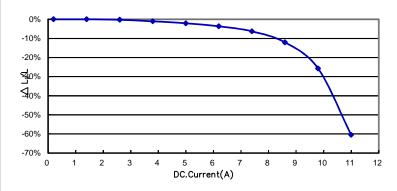
## CHARACTERISTICS OF TEMPERATURE RISE





Saturation Current(A)	8.80
SRF (MHz)	65
Temperature Rise Current (A)	4.95

## CURRENT VS INDUCTANCE DROP IN RATES



#### NOTES:

- 1.OPERATION TEMPERATURE RANGE: -40°C~+125°C (INCLUDING SELF-HEATING).
- 2.STORAGE TEMPERATURE RANGE (PACKAGING CONDITIONS): -10°C TO +40°C AND RH 70% (MAX.)
- 3.UNLESS OTHERWISE SPECIFIED, THE STANDARD ATMOSPHERIC CONDITIONS FOR MEASUREMENT/TEST AS:
  A. AMBIENT TEMPERATURE: 20±15°C.
- B. RELATIVE HUMIDITY: 65%±20%.
- 4.SATURATION CURRENT IS THE DC CURRENT AT WHICH THE INDUCTANCE DROPS OFF APPROXIMATELY 30% FROM ITS VALUE WITHOUT CURRENT.(AMBIENT TEMPERATURE 25±5°C)
- 5.TEMPERATURE RISE CURRENT (IRMS):

DC CURRENT THAT CAUSES THE TEMPERATURE RISE (△T ≤40°C) FROM 25°C AMBIENT.

	DIMENSIONS ARE IN mm .			This print is the property of Lair Tech. and is loaned in confidence subject to return upon request c with the understanding that no copies shall be made without the written consent of Laird Tech. Al rights to design or invention are reserved.	Laird				
				PROJECT/PART NUMBER:	- 1	REV	PART T		DRAWN BY:
С	CHANGE DIMENSIONS C/D/E	08/18/16		TYS60451R5N-10		С		WER ICTOR	QIU
В	CHANGE TEMP FROM&ADD CURVE	01/02/13		F 12707712 I	SCAL	E NTS		SHEET:	
Α	ORIGINAL DRAFT	12/07/12	QIU		TOOL				
REV	DESCRIPTION	DATE	INT			_		1	of 1